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(54) **ULTRASOUND TRANSDUCER ARRAYS WITH VARIABLE PATCH GEOMETRIES**

ULTRASCHALLWANDLERARRAYS MIT VARIABLEN PATCHGEOMETRIEN

RÉSEAUX DE TRANSDUCTEURS ULTRASONORES À GÉOMÉTRIES DE PLAQUES VARIABLES

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Description

[0001] This invention relates to medical diagnostic ultrasound systems and, in particular, to diagnostic systems with array transducers having elements grouped in patches and operating with a microbeamformer.

[0002] Ultrasound array transducers, transducers with a plurality of separately controllable transducer elements, have been developed in a number of configurations. Annular arrays are comprised of annular rings of elements and are well suited to transmit a tightly focused beam straight ahead, that is, normal to the plane of the transducer elements.

A 1D array of elements is comprised of a single row of elements (or multiple rows connected to operate in unison) which can scan a single image plane, an azimuth plane, normal to the row of elements. A 1.5D array comprises multiple rows of elements which can be operated symmetrically in elevation to scan an azimuth plane normal to the array but with beams that are focused electronically in both azimuth and elevation. A 2D (two dimensional) array comprises elements extending in both azimuth and elevation directions which can be operated fully independently to both focus and steer beams in any azimuth or elevation direction. Except for the annular array, these arrays can be configured in either flat or curved orientations. The present invention is directed to 2D array transducers which can steer and focus in both azimuth and elevation to scan a three dimensional volumetric region of interest.

[0003] Two dimensional array transducers and even 1D array with large numbers of elements pose a problem due to their large number of transducer elements. Since each of these elements must be individually controlled on transmit and receive, a separate signal line must be provided for each element. A 1D array may comprise a row of 100-200 elements, requiring 100-200 signal lines, which can be accommodated in a relatively small and light probe cable, but may need to operate with a system beamformer of relatively few channels. A 2D array may have 100-200 rows of elements in one dimension and 100-200 columns of elements in the other dimension, totaling thousands of individual elements. A cable of many thousands of signal lines is not practical for a probe which handheld and must be manipulated by the sonographer. An implementation of the present invention overcomes these problems by use of a microbeamformer integrated circuit attached to the 2D array which performs partial beamforming of groups of elements referred to as patches. The summed signal from the elements of each patch are then conducted over a standard size cable to the ultrasound system beamformer where the summed signal from each patch is applied to a channel of the system beamformer, which completes the beamforming operation. This partitioning of the full beamforming operation between a microbeamformer in the probe and the channels of the system beamformer, illustrated for instance in US Pat. 5,229,933 (Larson, III), enable the use

of a cable with a relatively few number of signal lines between the probe and the ultrasound system.

[0004] The number of elements used to receive echo signals from along a scanline can be selected and varied, thereby controlling the active aperture of the array. Much like an optical system, the number of elements in the active aperture relate to the f number of the aperture. As echoes are received from the near field immediately in front of the array, only a small number of elements can be used to receive the initial echo signals from a shallow depth of the beam. But as echoes are received from ever increasing depths, additional elements on either side of the initially used elements can be added in uniform increments to maintain the f number of the aperture and the sensitivity of the probe to echoes from greater depths. This dynamic aperture control is well understood for 1D arrays but becomes much more complex when a 2D array is used or multiline reception is needed. In multiline reception, echo signals received from transducer elements for multiple, spatially discrete lines are processed differently for the different lines and multiple receive lines are produced at the same time. See, for example, US Pat. 5,431,167 (Savord). A microbeamformer with multiple parallel processors for each transducer element of a 2D array would be exceedingly complex, expensive, and constrained by the space available in the handheld transducer probe. But multiline reception is highly desirable for many probes, particularly for a 2D array due to need to transmit and receive beams over a volumetric region within the time limit of an acceptable acquisition frame rate and the speed of sound is an immutable law of physics. Hence a technique is needed to be able to perform high order multiline reception while maintaining high quality, artifact-free performance.

[0005] US 5,677,491 A discloses a two-dimensional ultrasonic transducer having a plurality of transducer elements for producing ultrasonic bursts in a predetermined manner, and receiving reflected ultrasound from the subject under examination due to the ultrasonic bursts. The plurality of transducer elements are arranged in an array into columns and rows, the columns of the transducer elements arranged in a scanning plane for scanning the subject under examination, and the rows of the transducer elements having groups of symmetrically arranged transducer elements being oriented in a elevational plane. Each of the groups of symmetrically arranged transducer elements are mechanically arranged to have a focus at specified locations distant from the transducer which is within the subject under examination.

[0006] In accordance with the principles of the present invention, a method for controlling an aperture of an array transducer is provided according to claim 1.

[0007] The ultrasonic transducer array is operated with a microbeamformer to process signals from defined patches of transducer elements. During reception from the near field a first patch size is used, preferably the smallest patch size in most imple-

mentations. As echoes are received from increasing depths of field the aperture grows by adding patches of different and preferably progressively larger size to the active aperture as the patch acceptance angle for echoes from greater depths declines. An implementation of the present invention enables the reception of a high order of multilines without artifacts and image brightness discontinuities.

[0008] In the drawings:

FIGURE 1 illustrates in block diagram form a 2D curved array transducer and microbeamformer probe of the present invention.

FIGURE 2 is a block diagram illustrating the concept of a partial beamsum microbeamformer.

FIGURE 3a illustrates multiline reception with a 2D array transducer using uniform patch sizes.

FIGURE 3b illustrates multiline reception with a 2D array transducer using progressively larger patch sizes in accordance with the principles of the present invention.

FIGURE 3c is another illustration of the drawing of FIGURE 3b which highlights the beam profiles of the intermediate-sized patches.

FIGURE 4 illustrates the patch areas for azimuth scanning with a 2D array transducer constructed in accordance with the principles of the present invention.

FIGURE 5 illustrates the patch areas for elevation scanning with a 2D array transducer constructed in accordance with the principles of the present invention.

FIGURE 6 illustrates the patch areas of a 2D array transducer for use with a low channel count system beamformer which does not need multiline acquisition.

FIGURE 7 illustrates a cross point switch matrix for coupling patches of a 2D array of various sizes to a system beamformer in accordance with the principles of the present invention.

[0009] Referring first to FIGURE 1, an ultrasound system constructed in accordance with the principles of the present invention is shown in block diagram form. A probe 10 has a two dimensional array transducer 12 which is curved in the elevation dimension such as that shown in US Pat. 7,927,280 (Davidsen). The elements of the array are coupled to a microbeamformer 14 located in the probe behind the transducer array. The microbeamformer applies timed transmit pulses to elements of the array to transmit beams in the desired directions and to the desired focal points in the three dimensional image field in front of the array. Echoes from the transmitted beams are received by the array elements and coupled to channels of the microbeamformer 14 where they are individually delayed. The delayed signals from a patch of transducer elements are combined to form a partial sum signal for the patch. As used herein the term "patch" refers to

a group of transducer elements which are contiguous and operated together, or have their signals combined by a microbeamformer to form one signal for an ultrasound system beamformer. In a typical implementation combining is done by coupling the delayed signals from the elements of the patch to a common bus, obviating the need for summing circuits or other complex circuitry. The bus of each patch is coupled to a conductor of a cable 16, which conducts the partial sum patch signal to the system mainframe. In the system mainframe the partial sum signals are digitized and coupled to channels of a system beamformer 22, which appropriately delays each partial sum signal. The delayed partial sum signals are then combined to form a coherent steered and focused receive beam. The beam signals from the 3D image field are processed by a signal and image processor 24 to produce 2D or 3D images for display on an image display 30. Control of ultrasound system parameters such as probe selection, beam steering and focusing, and signal and image processing is done under control of a controller 26 which is coupled to various modules of the system. In the case of the probe 10 some of this control information is provided from the system mainframe over data lines of the cable 16. The user controls these operating parameters by means of a control panel 20.

[0010] FIGURE 2 illustrates the concept of a partially summing microbeamformer. The drawing of FIGURE 2 is sectioned into three areas by dashed lines 32 and 34. Components of the probe 10 are shown to the left of line 32, components of the system mainframe are shown to the right of line 34, and the cable 16 is shown between the two lines. The two dimensional array 12 of the probe is divided into patches of contiguous transducer elements. Five of the patches of the array 12 are shown in the drawing, each including nine neighboring elements. The microbeamformer channels for patches 12a, 12c, and 12e are shown in the drawing. The nine elements of patch 12a are coupled to nine delay lines of the microbeamformer indicated at DL1. Similarly the nine elements of patches 12c and 12e are coupled to the delay lines indicated at DL2 and DL3. The delays imparted by these delay lines are a function of numerous variables such as the size of the array, the element pitch, the spacing and dimensions of the patch, the range of beam steering, and others. The delay line groups DL1, DL2, and DL3 each delay the signals from the elements of their respective patch to a common time reference for the patch. The nine delayed signals from each group of delay lines are then combined by a respective summer Σ to form a partial sum signal of the array from the patch of elements. Each partial sum signal is put on a separate bus 15a, 15b, and 15c, each of which is coupled to a conductor of the cable 16, which conducts the partial sum signals to the system mainframe. In the system mainframe each partial sum signal is applied to a delay line 22a, 22b, 22c of the system beamformer 22. These delay lines focus the partial sum signals into a common beam

at the output of the system beamformer summer 22s. The fully formed beam is then forwarded to the signal and image processor for further processing and display. While the example of FIGURE 2 is shown with 9-element patches, it will be appreciated that a constructed microbeamformer system will generally have patches with larger numbers of elements such as 12, 20, 48, or 70 elements or more. The elements of a patch can be adjacent to each other, be spaced apart, or even intermingled in a checkerboard pattern, with "odd" numbered elements combined in one patch and "even" numbered elements combined in another. The patches can be square, rectangular, diamond-shaped, hexagonal, or any other desired shape.

[0011] FIGURE 3a illustrates a problem with multiline acquisition that can be addressed with an implementation of the present invention. FIGURE 3a illustrates a receive beam profile 60, the outline of the area or volume of an image field in which echoes are received down to a depth X in the field. Four multilines R_{1A} , R_{2A} , R_{1B} , and R_{2B} , are to be received on either side of the line at the center of the image field by an array transducer 12 which is operationally divided into five patches of equal size, 40, 42, 44, 46 and 48. As is illustrated by FIGURE 3a, the beam profile 60 of a set of uniformly sized patches 40-48 is a relatively narrow region in the center of the image field. Only the deepest depths of the two multilines closest to the field center, R_{1A} and R_{1B} , are within the receive beam profile. The rest of the extent of the R_{1A} and R_{1B} multilines and the full extent of the outer multilines R_{2A} and R_{2B} are beyond the receive beam profile. Consequently the received signals for these beams will be of low intensity, resulting in weakly received echo signals which will be only dimly shown in an image using these multilines. The resulting artifacts will appear as shimmering bands of light and dark streaks in the resultant ultrasound image.

[0012] In FIGURE 3b, patches of different sizes are progressively added to the aperture to provide full coverage of the received echoes for the multilines. The center patch 50 is the smallest, which gives it the greatest acceptance angle for received echoes and a receive beam profile 62 which is relatively shallow in depth yet laterally broad as shown in FIGURE 3b. The receive beam profile 62 for this small center patch is seen to cover the near field of all four multilines. The adjacent patches 52 and 54 on either side of the center patch 50 are added as echoes are received from greater depths and cover the reception of mid-depth echoes of all four multilines as shown in FIGURE 3c. The beam profiles 64A and 64B obtained with the addition of the two larger patches 52 and 54 are seen to span all four multilines. The beam profiles from each of the larger patches are also seen to be slightly steered toward the center of the image field to provide complete coverage of the scanned region. Finally, the outermost, even larger patches 56 and 58 are added to the active aperture. The receive beam profiles 66A and 66B obtained with these patches are shown in FIGURE 3b. These beam profiles extend

to the greatest depths of the image field, are seen to have the smallest acceptance angles of any of the beam profiles, and are also seen to be slightly steered toward the center of the image field to afford full coverage of the region being scanned. The combination of all of the patches of the different sizes afford full coverage of the image field, preventing reception of echoes from outside of a beam profile and resulting shimmering image artifacts.

[0013] While FIGURES 3b and 3c only illustrate one dimension of patches of an array transducer in accordance with the present invention, FIGURES 4-6 show topographic views of 2D arrays 12 which illustrate the dimensions of patches of exemplary 2D arrays of the present invention in both the azimuth (horizontal) and the elevation (vertical) dimensions. The 2D arrays 12 shown in these examples each comprise 160 elements in azimuth and 120 elements in elevation, a total of 19,200 elements in each 2D array. Four microbeamformer ASICs are used to do initial partial beamforming for each array. One ASIC is located behind each quadrant of an array as indicated by the faint lines 1-1 and 2-2 which delineate the ASIC boundaries. In FIGURES 4 and 5 the patches are outlined by the darker lines. In the Example of FIGURE 4 there are seven rows of patches and sixteen columns of patches. This full aperture area 36 is seen to occupy less than the full area of the 2D array 12 so that the aperture can be translated in incremental steps across the 2D array for other spatially different scanlines as described in my US Pat. 8,161,817 (Savord). The aperture 36 of patches in FIGURE 4 is seen to be at the left side of the 2D array and is then translated in steps to the right side.

[0014] The patches in the aperture 36 of FIGURE 4 are smallest in the center of the aperture and largest at the azimuth edges of the aperture. Each row of patches in this example is 22 elements high in the elevation dimension; each patch is thus 22 elements in elevation. In the azimuth dimension the center four patches are three elements in width as indicated by the bracket 70 across the four center columns of patches. The next outermost columns of patches 72 and 72' are 4 elements wide and the next columns 74 and 74' are 5 elements wide. Patch columns 76 and 76' are 7 elements in elevation and patch columns 78 and 78' are 10 elements in elevation. The next outer columns 80 and 80' are 12 elements in elevation and the outermost columns 82 and 82' at the elevational limits of the aperture 36 are 14 elements wide. Reception with the 2D array of FIGURE 4 would start by using the two or four small center patches initially at the shallowest depth, then progressively switching in the next adjacent patches on either side as echoes are received from greater depths until the full aperture of patches is active and used until the greatest desired depth of reception. This choice of patch arrangement is well suited for scanning a series of parallel or slightly tilted planes each extending in the azimuth direction across the volume being imaged.

[0015] If planes are to be scanned in the orthogonal direction, a set of planes which each extend in the elevation direction, a patch arrangement such as shown in FIGURE 5 can be used. The active aperture 36 of the 2D array 12 of FIGURE 5 has seven columns of patches extending in the elevation dimension which are uniformly sized in the azimuth (horizontal in the drawing) direction. In the elevation dimension the patch sizing varies from the smallest in the center of the aperture, the three rows of patches bracketed at 80 which are each six elements high in the elevation direction. The next outer patches indicated in rows 82 and 82' are each 12 elements high, and the next patches 84 and 84' are each 19 elements high. The two outermost rows at each elevation extreme, rows 86, 88, 86' and 88', are each 20 elements high. Scanning is performed by starting reception with the smallest patches 80 in the center, first one or all three, then progressively adding the adjacent patches in symmetrical pairs out from the center to grow the active aperture to the full aperture 36 at the greatest depth of field. As with the 2D array of FIGURE 4, the active aperture 36 in FIGURE 5 can be translated across the array in the azimuth direction to scan additional scanlines in the volumetric region in front of the array.

[0016] FIGURE 6 illustrates an example of use of this 19,200 element 2D array 12 for imaging with an ultrasound system with only seven beamformer channels. As FIGURE 6 shows, there are only seven patches 91-97 in the active aperture 36, the partially beamformed sum signals of each being coupled to a channel of the 7-channel beamformer of the ultrasound system. As before, the active aperture of seven patches can be translated to various other positions on the array. Each patch in this example comprises 1280 elements, 16 elements in the elevation direction and 80 elements in the azimuth direction. An aperture of this configuration would not generally be used for multiline scanning in azimuth, but could be used for low order multiline acquisition in elevation.

[0017] FIGURE 7 illustrates a cross point switching matrix suitable for selectively coupling microbeamformed signals from the probe microbeamformer 14 to channels of the system beamformer 22. Each element of the 2D array transducer, such as element 0, element 1, ... element 3000 is coupled to circuitry 14' of the microbeamformer 14 which imparts an appropriate delay to the received signals. Each delayed element signal is conducted by a line 112, 114, ... 120 to arms of electronic switches such as 122, 124, ... 126 and 132, 134, ... 136. One of the electronic switches on the line is closed to couple the signal from that element to a selected system beamformer channel such as system channel 0, system channel 1, ... system channel 2. By selectively closing a desired switch in the cross point switching matrix, any delayed element signal can be put on a bus 102, 104, ... 110 to sum with other signals on the bus and be applied to a channel of the system beamformer 22 for completion of the beamforming operation.

[0018] While the use of the present invention is partic-

ularly desirable when the probe uses a 2D array transducer, it is also advantageous for probes using 1D arrays which operate with a microbeamformer in the probe. Such an arrangement can be operated with ultrasound system beamformers of very low channel count such as system beamformers of only eight, ten, or twelve channels as described in US patent application serial number 61/503,329 (Poland et al.), filed June 30, 2011. An implementation of the present invention can improve the multiline performance of 1D array/microbeamformer probes in systems with reduced channel count such as these.

15 Claims

1. A method for controlling the aperture of an array transducer of an ultrasound probe, wherein the array transducer comprises a two dimensional (2D) array of transducer elements, the transducer elements of the array being coupled to a microbeamformer in the probe which performs at least partial beamforming of received echo signals, the method comprising:

configuring the aperture of the array into patches of different sizes, each patch comprising a group of transducer elements coupled to the microbeamformer;

receiving echoes from a shallow depth of field with an aperture of one or more patches of a first, relatively small size;

receiving echoes from a deeper depth of field by growing the aperture to add patches of a larger size than the first, relatively small size,

characterized in that the configuring further comprises either

(i) configuring patches of a uniform size in the elevation dimension and different sizes in the azimuth dimension, such that a smallest patch is positioned in a center of the aperture in the azimuth dimension with patches of progressively increasing size extending on either side of that smallest patch to the azimuth limits of the aperture on either side of that smallest patch, or

(ii) configuring patches of a uniform size in the azimuth dimension and different sizes in the elevation dimension, such that a smallest patch is positioned in a center of the aperture in the elevation dimension with patches of progressively increasing size extending on either side of that smallest patch to the elevation limits of the aperture on either side of that smallest patch.

2. The method of Claim 1, wherein receiving echoes from a deeper depth of field further comprises grow-

ing the aperture to add patches of a second, larger size on either side of one or more patches of the first, relatively small size.

3. The method of Claim 2, wherein receiving echoes from a deeper depth of field further comprises growing the aperture symmetrically about the one or more patches of a relatively small size. 5
4. The method of Claim 2, wherein receiving echoes from a deeper depth of field further comprises growing the aperture to add patches of a largest size on either side of the patches of a larger size. 10
5. The method of Claim 1, further comprising translating the aperture to different groups of transducer elements of the 2D array. 15
6. The method of Claim 1, further comprising partially beamforming the signals from the elements of a patch with the microbeamformer; and completing the beamforming of the partially beamformed signals with an ultrasound system beamformer. 20
7. The method of Claim 1, further comprising processing the signals from the elements of a patch with a microbeamformer to form a patch sum signal; and coupling the patch sum signal to a channel of an ultrasound system beamformer. 25
8. The method of Claim 7, further comprising coupling the signals from the elements of a patch to a channel of an ultrasound system beamformer with a cross point switch. 30
9. The method of Claim 7, wherein forming a patch sum signal further comprises coupling the signals from the elements of a patch to a common bus. 35
10. The method of Claim 7, wherein processing the signals from the elements of a patch further comprises delaying the signals from the elements. 40

Patentansprüche

1. Verfahren zum Steuern der Öffnung eines Array-Wandlers einer Ultraschallsonde, wobei der Array-Wandler ein zweidimensionales (2D) Array von Wandlerelementen umfasst, wobei die Wandlerelemente des Arrays mit einem Mikrostrahlformer in der Sonde gekoppelt sind, der mindestens teilweise das Strahlformen der empfangenen Echosignale durchführt, wobei das Verfahren umfasst: 50

Konfigurieren der Öffnung des Arrays in Patches unterschiedlicher Größen, wobei jedes

Patch eine Gruppe von mit dem Mikrostrahlformer gekoppelten Wandlerelementen umfasst; Empfangen von Echos von einer flachen Feldtiefe mit einer Öffnung von einem oder mehreren Patches einer ersten, im Verhältnis kleinen Größe; Empfangen von Echos von einer tieferen Feldtiefe durch Steigern der Öffnung, um Patches einer größeren Größe als die erste, im Verhältnis kleine Größe hinzuzufügen, **dadurch gekennzeichnet, dass** das Konfigurieren weiter umfasst, entweder

(i) Konfigurieren von Patches einer einheitlichen Größe in der Elevationsdimension und von unterschiedlichen Größen in der Azimut-Dimension, sodass ein kleinstes Patch in einer Mitte der Öffnung in der Azimut-Dimension mit Patches von schrittweise zunehmender Größe, die sich auf beide Seiten dieses kleinsten Patch zu den Azimut-Grenzen der Öffnung auf beiden Seiten dieses kleinsten Patches erstrecken, positioniert ist, oder

(ii) Konfigurieren von Patches einer einheitlichen Größe in der Azimut-Dimension und von unterschiedlichen Größen in der Elevationsdimension, sodass ein kleinstes Patch in einer Mitte der Öffnung in der Elevationsdimension mit Patches von schrittweise zunehmender Größe, die sich auf beide Seiten dieses kleinsten Patch zu den Elevationsgrenzen der Öffnung auf beiden Seiten dieses kleinsten Patches erstrecken, positioniert ist.

2. Verfahren nach Anspruch 1, wobei das Empfangen von Echos von einer tieferen Feldtiefe weiter das Steigern der Öffnung umfasst, um Patches einer zweiten, größeren Größe an beiden Seiten von einem oder mehreren Patches der ersten, im Verhältnis kleinen Größe hinzuzufügen.
3. Verfahren nach Anspruch 2, wobei das Empfangen von Echos von einer tieferen Feldtiefe weiter das Steigern der Öffnung symmetrisch über das eine oder die mehreren Patches einer im Verhältnis kleinen Größe umfasst. 45
4. Verfahren nach Anspruch 2, wobei das Empfangen von Echos von einer tieferen Feldtiefe weiter das Steigern der Öffnung umfasst, um Patches einer größten Größe an beiden Seiten der Patches einer größeren Größe hinzuzufügen. 50
5. Verfahren nach Anspruch 1, weiter umfassend das Übertragen der Öffnung auf verschiedene Gruppen von Wandlerelementen des 2D-Arrays. 55

6. Verfahren nach Anspruch 1, weiter umfassend das teilweise Strahlenformen der Signale von den Elementen eines Patches mit dem Mikrostrahlformer; und Vervollständigen des Strahlenformens der teilweise strahlengeformten Signale mit einem Strahlenformer eines Ultraschallsystems. 5
7. Verfahren nach Anspruch 1, weiter umfassend das Verarbeiten der Signale von den Elementen eines Patches mit einem Mikrostrahlformer, um ein Patch-Summensignal zu formen; und das Koppeln des Patch-Summensignals mit einem Kanal eines Strahlenformers eines Ultraschallsystems. 10 15
8. Verfahren nach Anspruch 7, weiter umfassend das Koppeln des Signals von den Elementen eines Patches mit einem Kanal eines Strahlenformers eines Ultraschallsystems mit einem Kreuzpunktschalter. 20
9. Verfahren nach Anspruch 7, wobei das Formen eines Patch-Summensignals weiter umfasst das Koppeln der Signale von den Elementen eines Patches mit einem gemeinsamen Bus. 25
10. Verfahren nach Anspruch 7, wobei das Verarbeiten der Signale von den Elementen eines Patches weiter umfasst das Verzögern der Signale von den Elementen. 30

Revendications

1. Procédé pour commander l'ouverture d'un transducteur de réseau d'une sonde à ultrasons, dans lequel le transducteur de réseau comprend un réseau bidimensionnel (2D) d'éléments transducteurs, les éléments transducteurs du réseau étant couplés à un dispositif de formation de micro faisceau dans la sonde qui effectue une formation de faisceau au moins partielle de signaux d'écho reçus, le procédé comprenant : 35 40
 - la configuration de l'ouverture du réseau en plaques de tailles différentes, chaque plaque comprenant un groupe d'éléments transducteurs couplés au dispositif de formation de micro faisceau ; 45
 - la réception d'échos en provenance d'une profondeur de champ peu importante avec une ouverture d'une ou plusieurs plaques d'une première petite taille, relativement petite ; 50
 - la réception d'échos en provenance d'une profondeur de champ plus importante en cultivant l'ouverture pour ajouter des plaques d'une taille plus grande que la première taille, relativement petite, 55

caractérisé en ce que la configuration comprend en outre l'une ou l'autre de

- (i) la configuration de plaques d'une taille uniforme dans la dimension d'élévation et de tailles différentes dans la dimension d'azimut, de sorte qu'une plaque la plus petite est positionnée dans un centre de l'ouverture dans la dimension d'azimut avec des plaques de taille progressivement croissante s'étendant de chaque côté de cette plaque la plus petite jusqu'aux limites d'azimut de l'ouverture de chaque côté de cette plaque la plus petite, ou
 - (ii) la configuration de plaques d'une taille uniforme dans la dimension d'azimut et de tailles différentes dans la dimension d'élévation, de sorte qu'une plaque la plus petite est positionnée dans un centre de l'ouverture dans la dimension d'élévation avec des plaques de taille progressivement croissante s'étendant de chaque côté de cette plaque la plus petite jusqu'aux limites d'élévation de l'ouverture de chaque côté de cette plaque la plus petite.
2. Procédé selon la revendication 1, dans lequel la réception d'échos en provenance d'une profondeur de champ plus importante comprend en outre la croissance de l'ouverture pour ajouter des plaques d'une seconde taille plus grande de chaque côté d'une ou plusieurs plaques de la première taille relativement petite.
 3. Procédé selon la revendication 2, dans lequel la réception d'échos en provenance d'une profondeur de champ plus importante comprend en outre la croissance de l'ouverture de façon symétrique autour de la ou des plusieurs plaques d'une taille relativement petite.
 4. Procédé selon la revendication 2, dans lequel la réception d'échos en provenance d'une profondeur de champ plus importante comprend en outre la croissance de l'ouverture pour ajouter des plaques d'une taille la plus grande de chaque côté des plaques d'une taille plus grande.
 5. Procédé selon la revendication 1, comprenant en outre la translation de l'ouverture vers différents groupes d'éléments transducteurs du réseau 2D.
 6. Procédé selon la revendication 1, comprenant en outre une formation partielle de faisceau sur les signaux en provenance des éléments d'une plaque avec le dispositif de formation de micro faisceau ; et l'achèvement de la formation de faisceau des signaux ayant partiellement subi une formation de fais-

ceau avec un dispositif de formation de faisceau de système à ultrasons.

7. Procédé selon la revendication 1, comprenant en outre le traitement des signaux en provenance des éléments d'une plaque avec un dispositif de formation de microfaisceau pour former un signal de somme de plaque ; et le couplage du signal de somme de plaque à un canal d'un dispositif de formation de faisceau de système à ultrasons. 5 10
8. Procédé selon la revendication 7, comprenant en outre le couplage des signaux en provenance des éléments d'une plaque à un canal d'un dispositif de formation de faisceau de système à ultrasons avec un commutateur à point de croisement. 15
9. Procédé selon la revendication 7, dans lequel la formation d'un signal de somme de plaque comprend en outre le couplage des signaux en provenance des éléments d'une plaque à un bus commun. 20
10. Procédé selon la revendication 7, dans lequel le traitement des signaux en provenance des éléments d'une plaque comprend en outre le retard des signaux en provenance des éléments. 25

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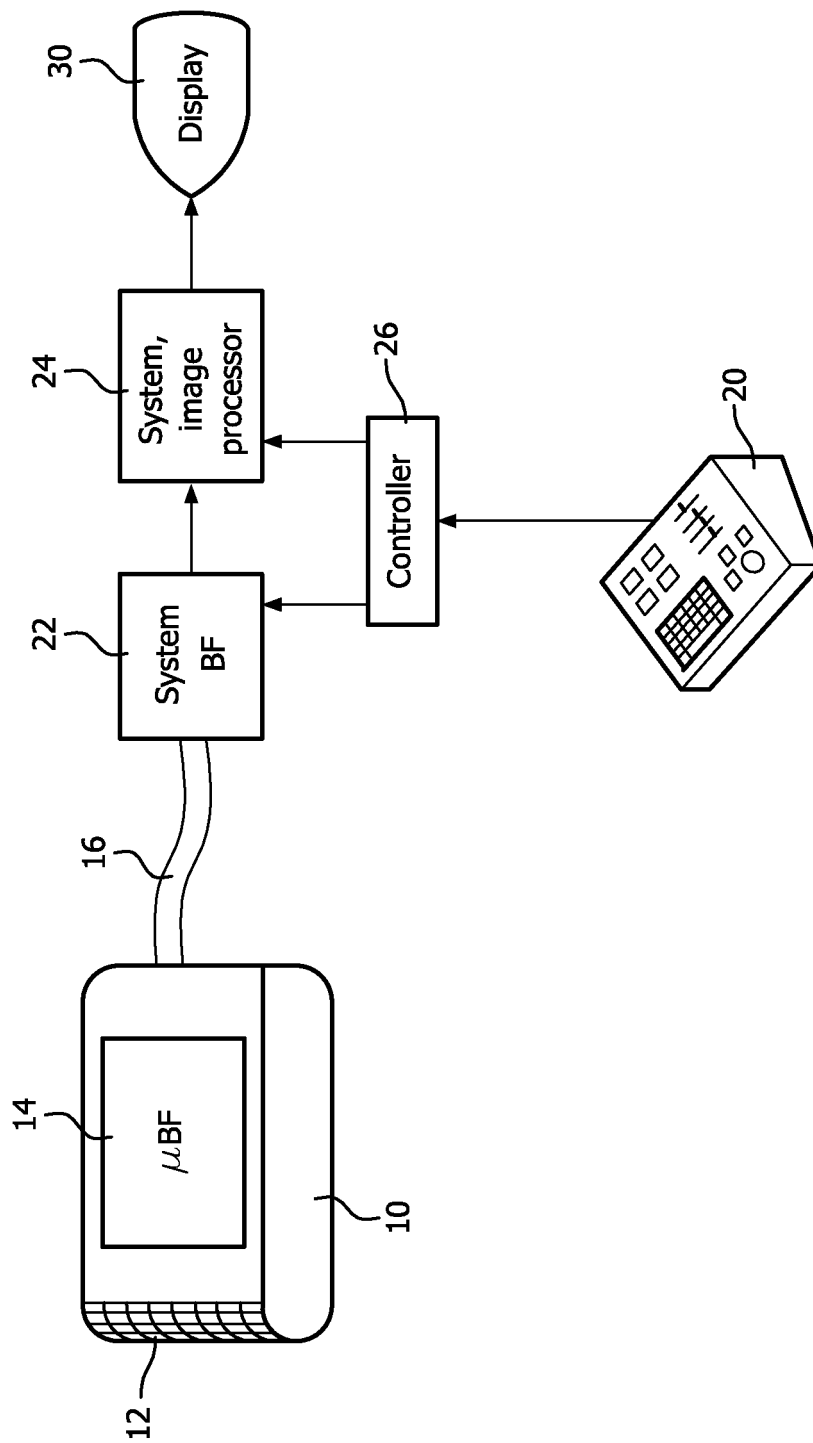


FIG. 1

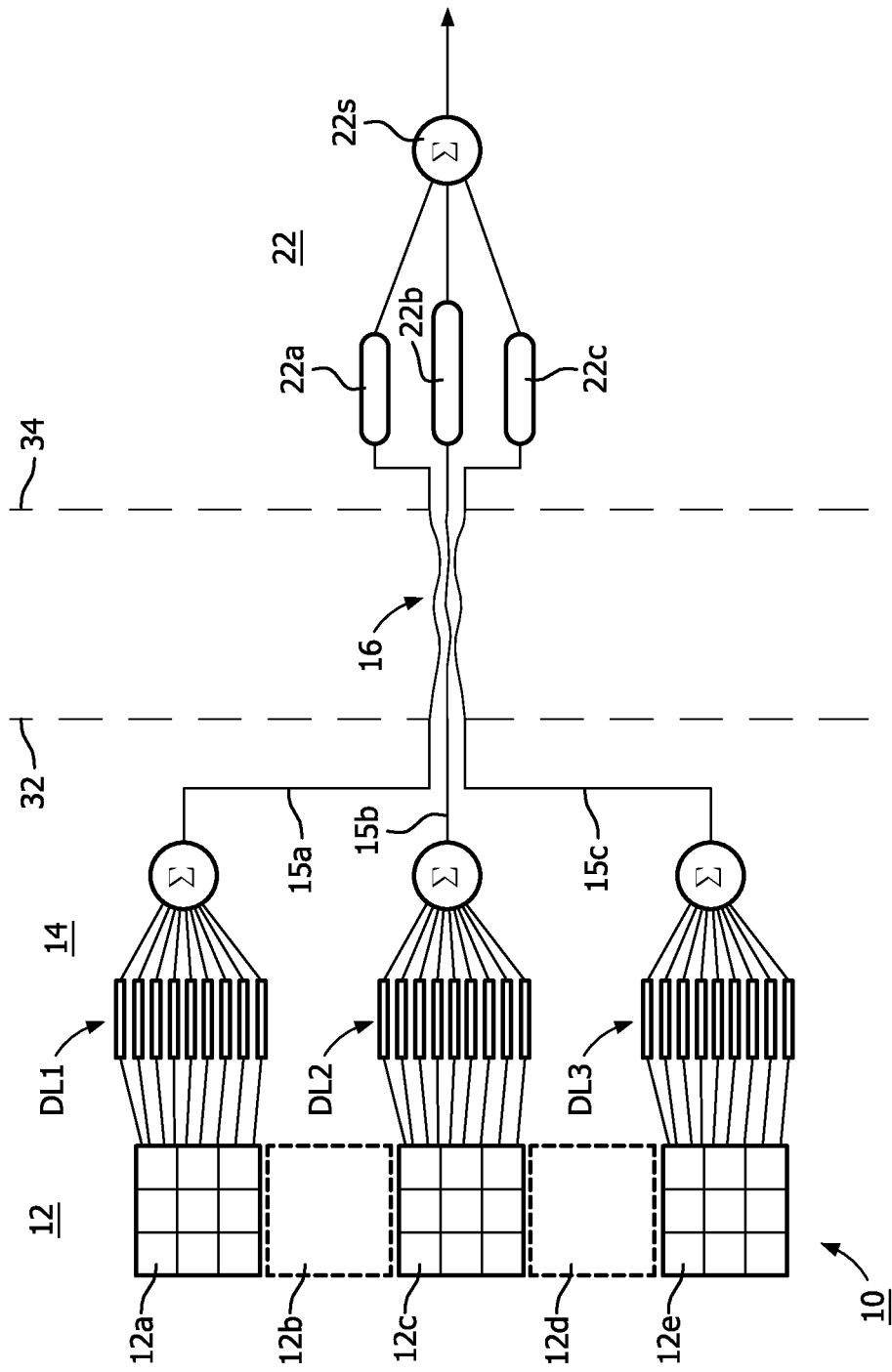


FIG. 2

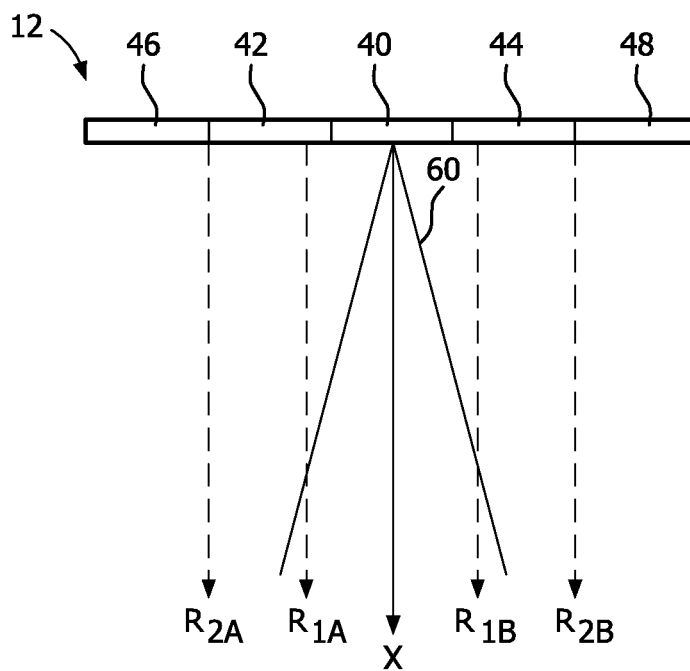


FIG. 3a

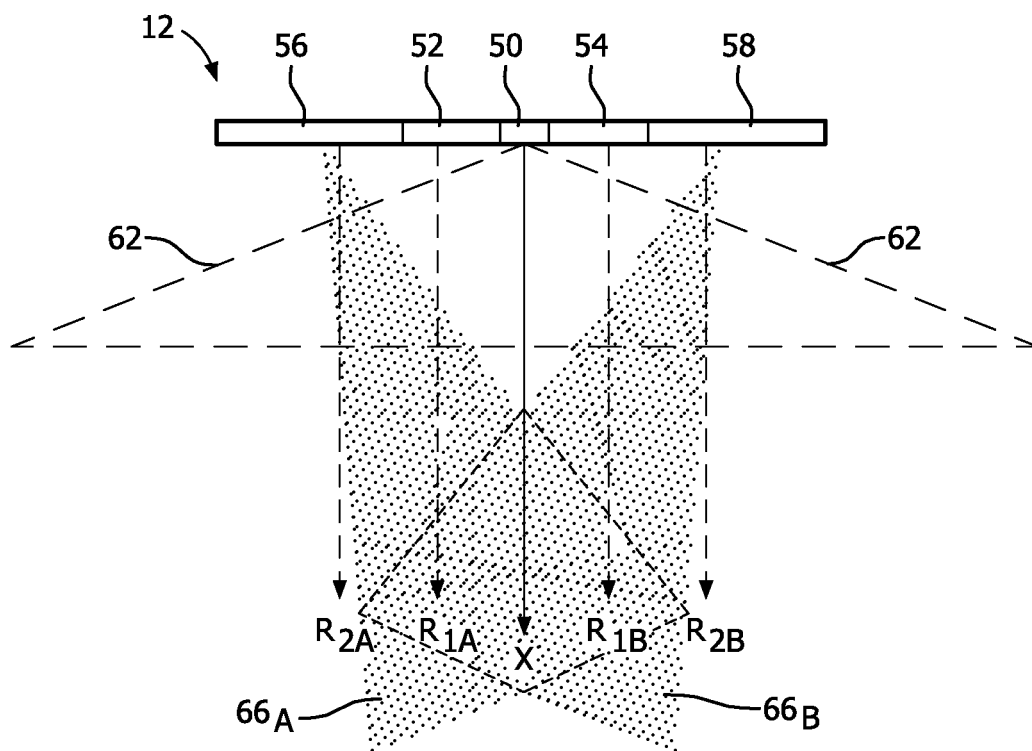


FIG. 3b

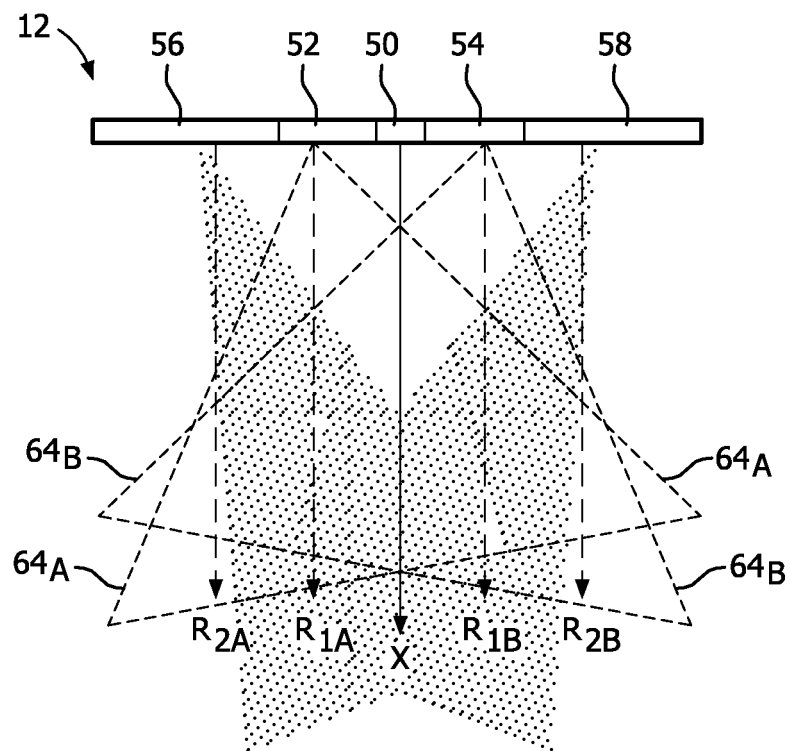


FIG. 3c

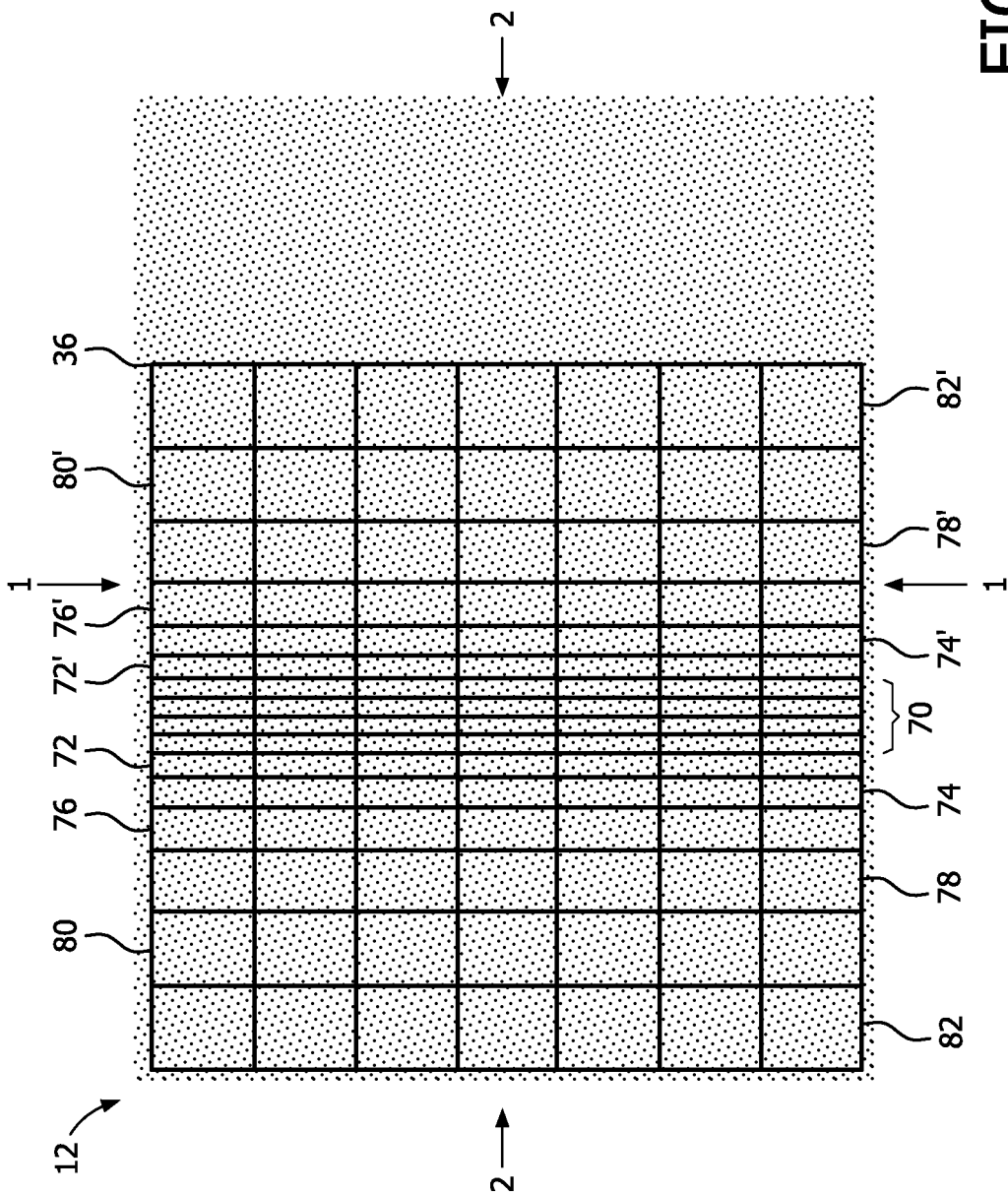


FIG. 4

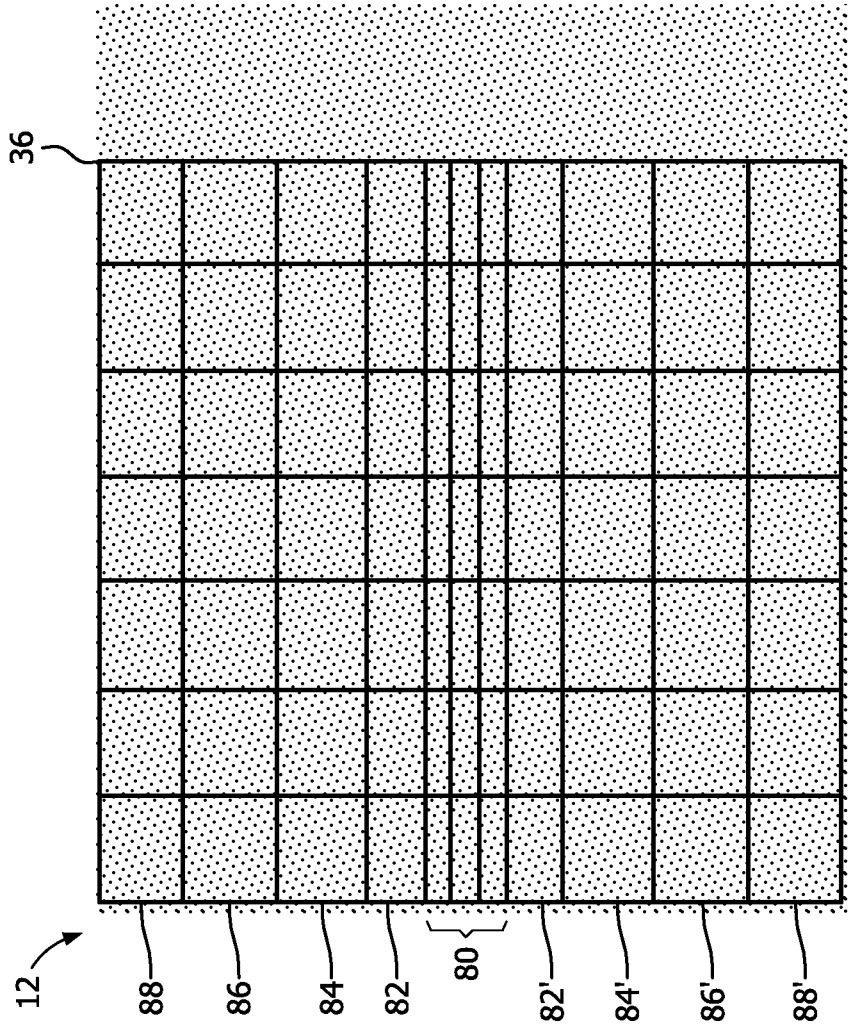


FIG. 5

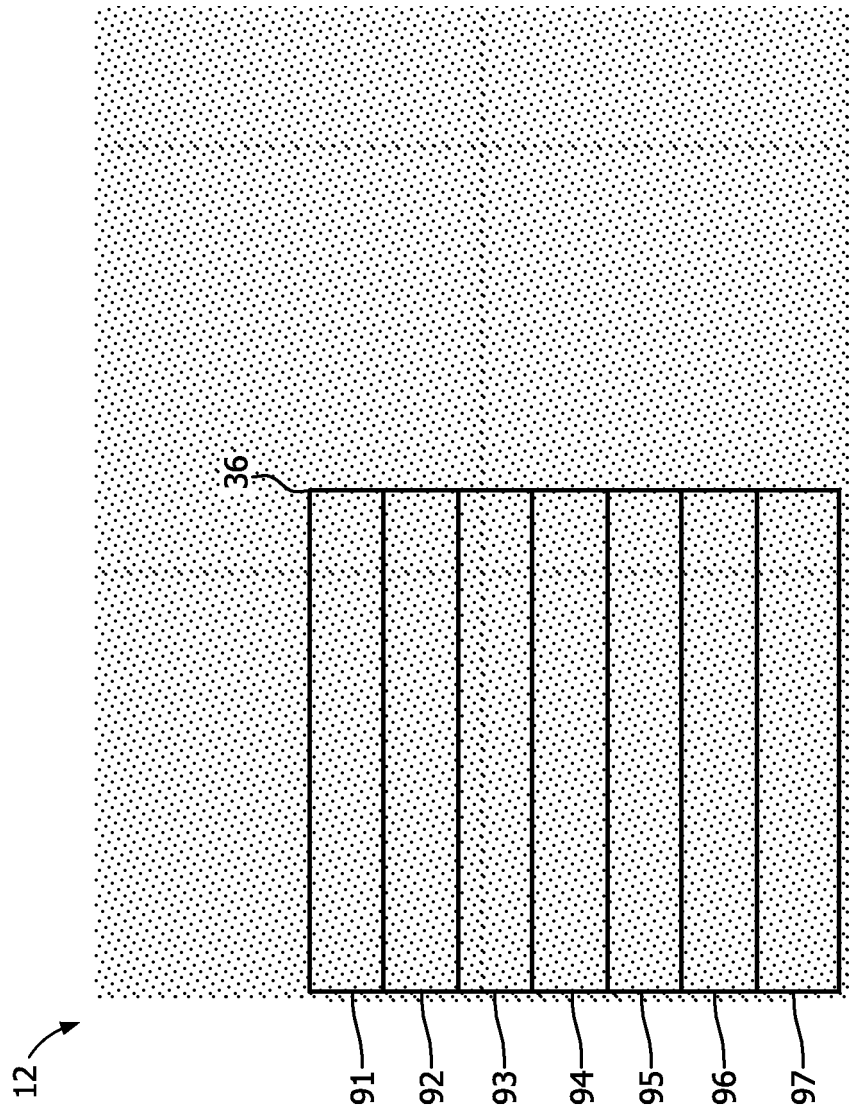


FIG. 6

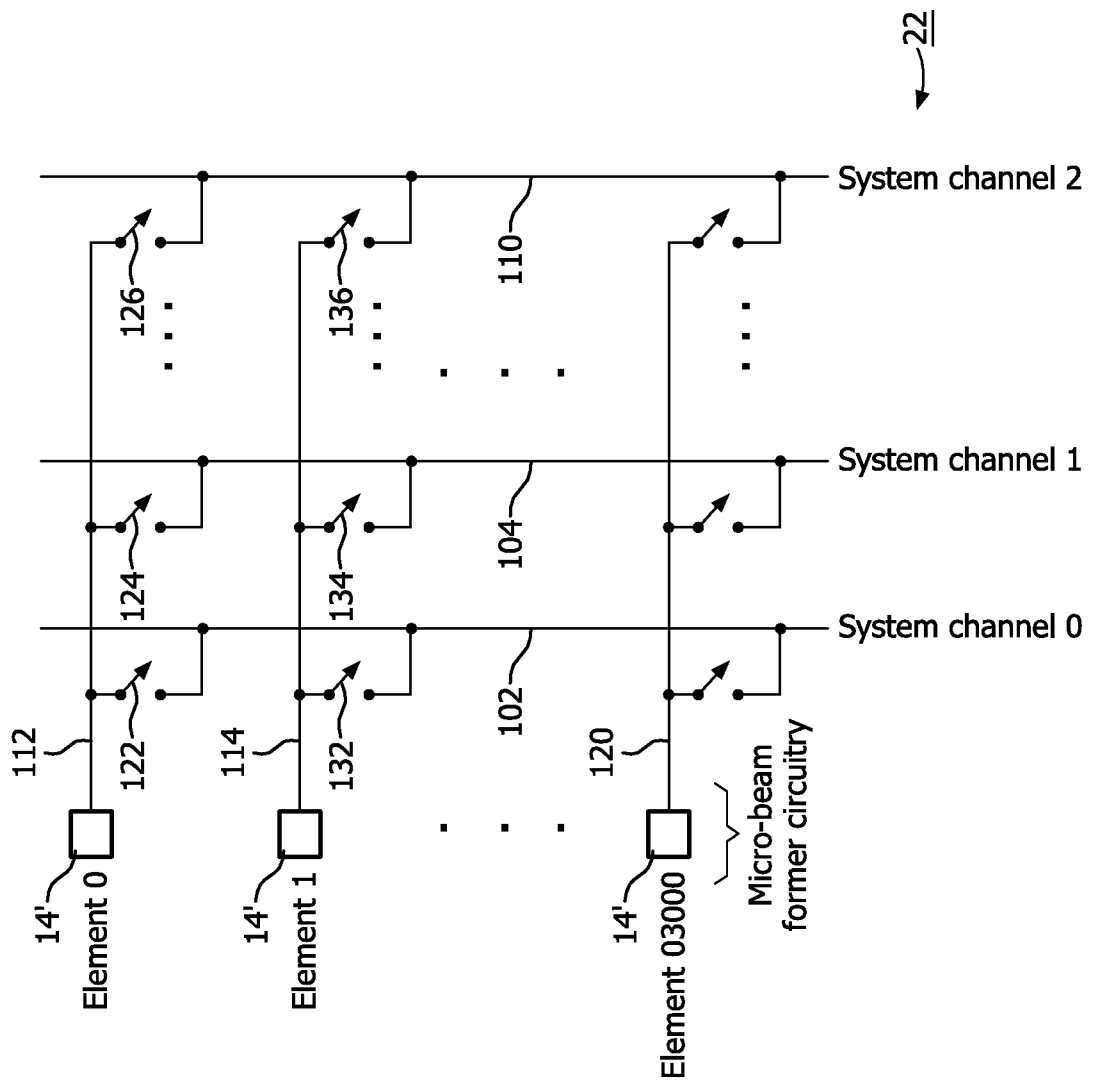


FIG. 7

REFERENCES CITED IN THE DESCRIPTION

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专利名称(译)	具有可变贴片几何形状的超声换能器阵列		
公开(公告)号	EP2847615B1	公开(公告)日	2019-04-03
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[标]申请(专利权)人(译)	皇家飞利浦电子股份有限公司		
申请(专利权)人(译)	皇家飞利浦N.V.		
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优先权	61/644524 2012-05-09 US		
其他公开文献	EP2847615A1		
外部链接	Espacenet		

摘要(译)

二维超声阵列换能器接收来自体积区域的增加深度的回波信号。2D阵列被配置成由微波束形成器处理的元件块，并且来自贴片的求和信号耦合到超声波束形成器的通道。在最浅的深度处，2D阵列从孔径的中心接收来自小块的回波。当从增加的深度接收信号时，通过在中心的小块的任一侧上对称地添加逐渐增大的尺寸的块来生长孔径。本发明的技术可以改善1D和2D阵列探针的多线性能。

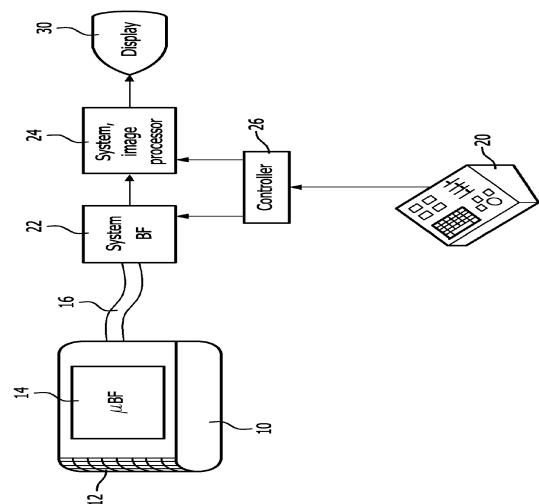


FIG. 1